

PART NUMBER

COMPONENT SPECIFICATION



Component Specification For Ceramic Hermetically Sealed, Radiation Hard Transistor Optocoupler

Features	Applications
 Radiation Tolerance tested to 150 Krad(si) Hermetically Sealed High Isolation up to 1,000V_{DC} LCC-6 Low input requirements High Current Transfer Ratio 	 Space Equipment and Systems Military and Hi-reliability Systems Medical Instruments MOS/CMOS Applications Logic Interfacing Data Transmission Power Supply Modems

DESCRIPTION

This device is a single channel, hermetically sealed optically coupled isolator. It is composed of a Gallium Arsenide infrared emitting diode and a silicon phototransistor.

The CSM1200 series is being used in environments encountered by space applications. Package styles for this device include an LCC-6 package, with solder dip option available.

Absolute maximum ratings, recommended operating conditions, electrical specifications and performance characteristics are identical for all units. Any exceptions, due to packaging variations and limitations, are as noted.







aerospace sector certification scheme



ISOCOM Limited is AS9100 certified for the design and manufacture of electronic and optoelectronic components.



STANDARDS

The following specifications have been included in the manufacturing of this product:

Aerospace Compliance Standards

AS9100D / ISO 9001:2015 – Design & Manufacture of Electronic and Optoelectronic Components (Ref GB15/92780)

Military Compliance Specifications

MIL-PRF-38534 – General Specification for Hybrid Microcircuits MIL-PRF-19500 – General Specification for Discrete Semiconductor Devices

Military Compliance Standards

MIL-STD-202 - Test Method Standard Electronic and Electrical Component Parts

MIL-STD-883 - Test Method Standard Microcircuits

MIL-STD-750 - Test Method Standard for Semiconductor Devices.

LOT DEFINITIONS

The <u>Assembly Lot</u> is a quantity of components that are manufactured with semiconductor dice out of one diffusion lot, with a piece part out of one piece part lot, using the basic raw material out of one raw material lot and an interrupted period of time to the end of the production tests which includes the same process, specifications and procedures using the same equipment and personal on the same design, construction and geometry.

SCREENING INFORMATION

Our products can be screened to MIL-PRF-38534, applying test methods from MIL-STD-883; MIL-PRF-19500, applying test methods of MIL-STD-750; or a combination thereof. Please contact us for more information relating to the applicable screening processes.

AMENDMENT RECORD

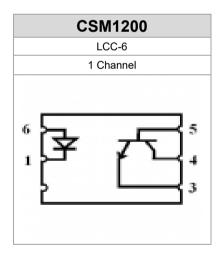
Issue No.	Date	Description
1	August 2013	First issue
2	May 2019	Updated 'Standards' section, Screening and Group Test Information removed.
3	September 2020	Updated Quality Management Logos and removed IECQ Logos
4	May 2022	Added Radiation Testing and Electrical Testing Diagrams, Updated Format, Added Render
5	June 2022	Updated Electrical Characteristics Graphs and Added Screening Flows
6	August 2022	Updated Formatting
7	August 2023	Added pin configuration, updated screening, updated circuit drawings and device marking.



SELECTION GUIDE PACKAGE STYLES AND CONFIGURATION OPTIONS

ISOCOM Part Number and Options					
Package	LCC-6				
Lead Style	_				
Channels	1				
Common Channel Wiring	_				
Commercial	CSM1200				
Defense Screen Level	CSM1200/L2				
Space Screen Level	CSM1200/L2S				
Standard Finish	Gold Plating				
Butt Joint	_				
Solder Dipped	Option 20				
Gull Wing	_				
Butt Joint	_				

FUNCTIONAL DIAGRAMS

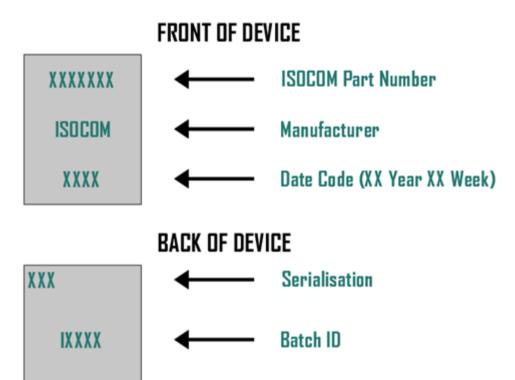


PIN OUT

Pin number	Function
1	Cathode
2	NC
3	Emitter
4	Collector
5	Base
6	Anode



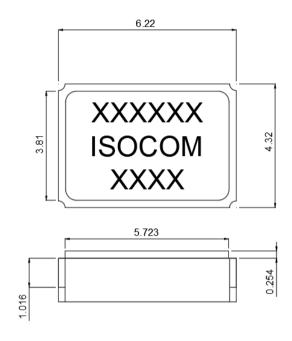
DEVICE MARKING

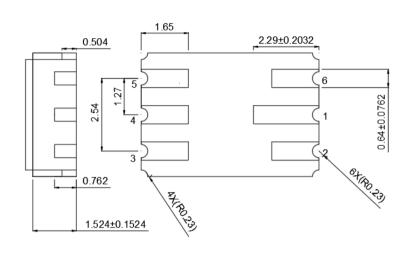


FOR SPACE SCREENED PARTS ONLY



DUTLINE DRAWINGS





ABSOLUTE MAXIMUM RATINGS

T_A = 25°C U.O.S.

Storage Temperature	-65°C to +150°C
Operating Temperature	-55°C to +125°C
Lead Soldering Temperature	260°C 1.6mm from case for 10s
Input-to-Output Isolation Voltage	। ऐ1,000V _{DC}

Input Diode

Average Forward Current	50mA	
Reverse Voltage	7V	
Peak forward Current	1.5A	≤1µs
Power Dissipation	100mW	Derate linearly 1.6mW/°C above 100°C

Output Transistor

Supply Voltage	0.5V to 20V	
Average Current	8mA	
Collector Current	50mA	
Power Dissipation	150mW	



ELECTRICAL CHARACTERISTICS

T_A = -55°C - 125°C U.O.S.

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Input Diode Electric	al Charact	eristics				
Forward Voltage	V _F	I _F = 10mA	0.7	1.2	1.8	V
Reverse Current	I _R	V _R = 3.0V	-	-	100	μΑ
Output Detector Ele	ctrical Cha	aracteristics	I			
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	I _C = 0.1mA	70	100	-	V
Collector-Base Breakdown Voltage	V _{(BR)CBO}	Ι _Β = 100μΑ	70	200	-	V
Emitter-Collector Breakdown Voltage	V _{(BR)ECO}	I _E = 0.1mA	7	9	-	V
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	I _B = 1mA	5	-	-	V
Collector–Emitter Leakage Current	I _{CEO}	$V_{CE} = 20V, I_F = 0A$	-	7	100	μΑ
Coupled Electrical (Characteris	stics				
		I _F = 1.0mA, V _{CE} = 1V	200	-	-	%
	I _C /I _F	I _F = 3.0mA, V _{CE} = 1V	200	-	-	%
DC Current Transfer Ratio		I _F = 15.0mA, V _{CE} = 1V	100	-	-	%
(Pre-Radiation)		I _F = 10.0mA, V _{CE} = 5V	350	-	-	%
		I _F = 15.0mA, V _{CE} = 5V	100	-	-	%
		I _F = 1.0mA, V _{CE} = 15V	300			%
Collector-Emitter Saturation Voltage	V _{CE(Sat)}	I _C = 10.0 mA I _F = 20 mA	-	-	0.22	V
Isolation Voltage (1)	V in-out	T = 5s	1,500	-	-	V _{DC}
Input to Output Resistance (1)	R in-out	V _{IO} = 500V	-	10 ¹¹		Ω
Rise Time	t _r	$R_L = 100\Omega$, $V_{CC} = 10V$, $I_F = 10mA$	-	6	12	μs
Fall Time	t _f	$R_L = 100\Omega$, $V_{CC} = 10V$, $I_F = 10mA$	-	6	12	μs
Propagation Delay – H-L	t _{PHL}	$R_L = 100\Omega$, $V_{CC} = 10V$, $I_F = 10mA$	-	-	5.0	μs
Propagation Delay – L-H	t _{PLH}	$R_L = 100\Omega$, $V_{CC} = 10V$, $I_F = 10mA$	-	-	5.0	μs
		I _F = 1.0mA, V _{CE} = 1V	200	-	-	%
		I _F = 3.0mA, V _{CE} = 1V	100	-	-	%
DC Current Transfer Ratio	in	I _F = 15.0mA, V _{CE} = 1V	66	-	-	%
(Post-Radiation)	I _{C/} I _F	I _F = 10.0mA, V _{CE} = 5V	160	-	-	%
		I _F = 15.0mA, V _{CE} = 5V	40	-	-	%
		I _F = 1.0mA, V _{CE} = 15V	250	_	_	%

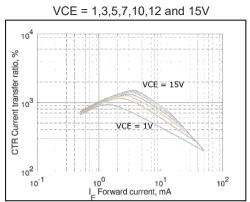
Notes:

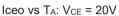
^{1.} Measurements with inputs shorted together and outputs shorted together.

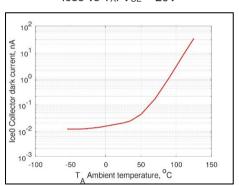


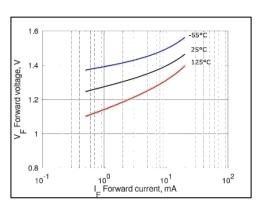
ELECTRICAL CHARACTERISTICS

Typical Graphs – Contact Office for more information

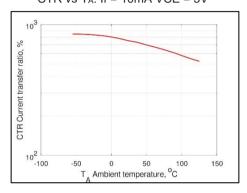




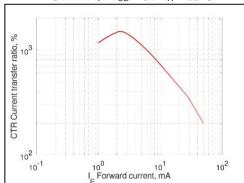




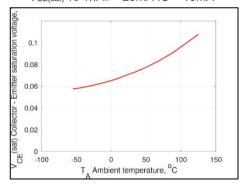
CTR vs T_A: If = 10mA VCE = 5V



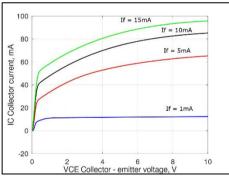




V_{CE(sat)} vs T_A: If = 20mA IC = 10mA

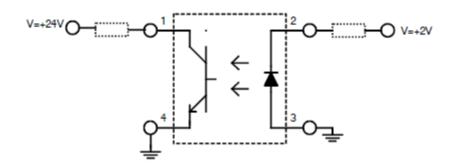


 I_C vs V_{CE} : $T_A = 25^{\circ}C$

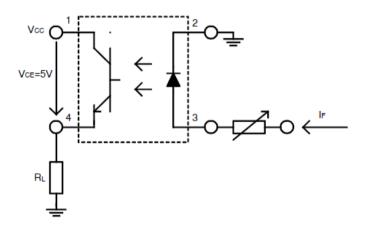




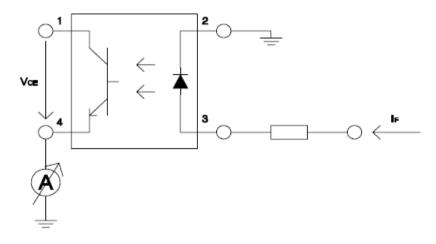
HTRB TEST CIRCUIT



ELECTRICAL CIRCUIT FOR BURN-IN AND OPERATING LIFE TESTS

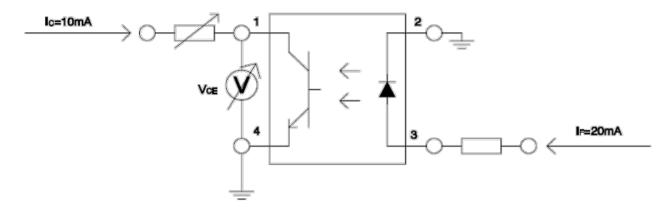


ELECTRICAL MEASUREMENT OF COLLECTOR CURRENT

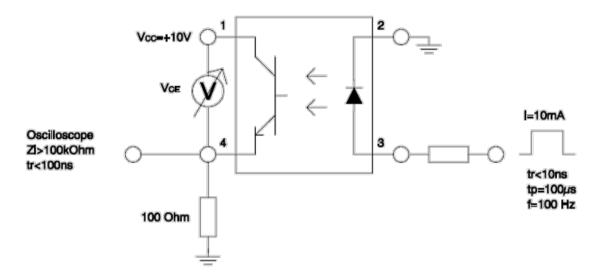




ELECTRICAL MEASUREMENT OF COLLECTOR EMITTER SATURATION VOLTAGE

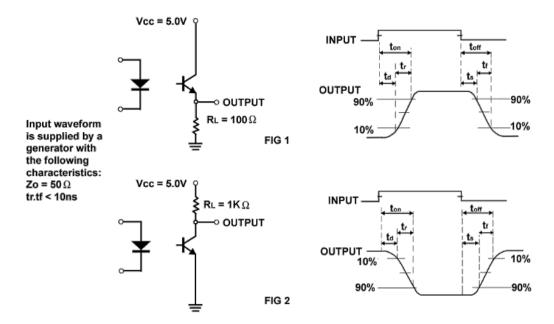


ELECTRICAL MEASUREMENT OF A.C PARAMETERS

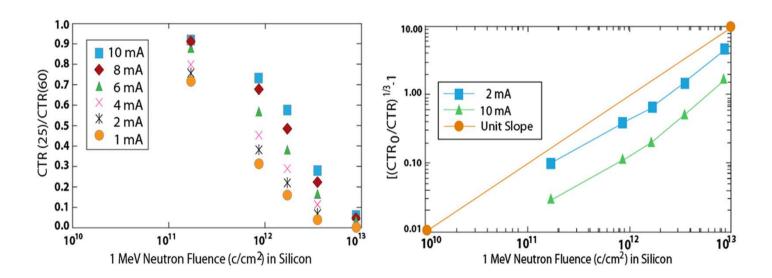




SWITCHING TIME

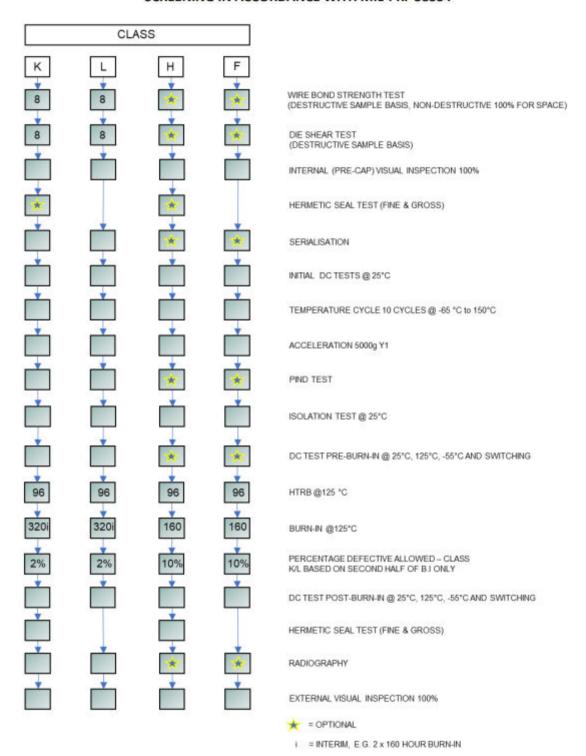


RADIATION TESTING





SCREENING IN ACCORDANCE WITH MIL-PRF 38534



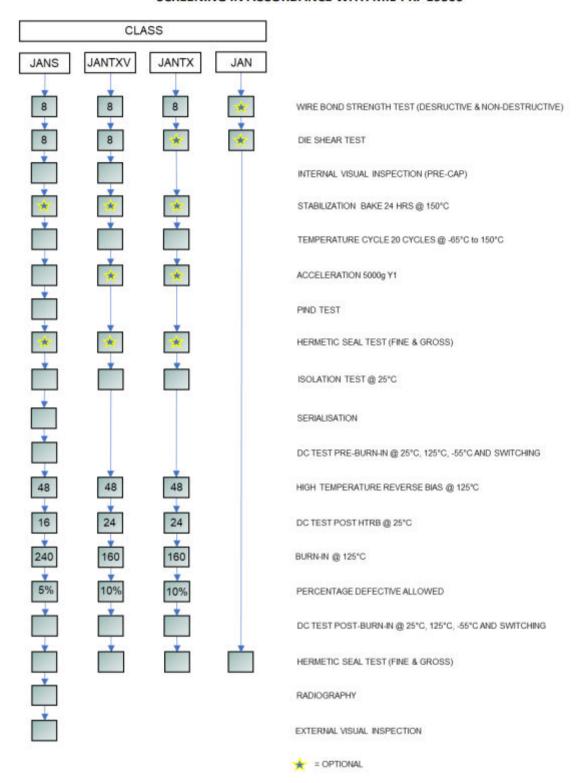


The following screening flow includes the electrical tests between each screening step, the referenced test method from MIL-STD 883 and the sample basis for Class K/L and H/F quality levels.

Operation No.	Operation	MIL-STD 883 TEST METHOD	Class		
	3 30 M (1995)		H/F (L2)	K/L (L25	
4	Wire bond strength (ND)	(883) 2023	Optional	100%	
2	Wire bond strength (D)	(883) 2011	Optional	8 devices	
3	Die Shear	(883) 2019	Optional	8 devices	
4	Internal Visual	(883) 2017	100%	100%	
5	Fine leak, Helium bomb, Leak detector	(883) 1014, Con A1	Optional	Optional	
6	Gross leak, Liquid bomb, -Bubble chamber	(883) 1014, Con C1	Optional	Optional	
7	Serialisation of devices		Optional	100%	
8	Electrical Test 25°C		100%	100%	
9	Temp cycle @ -65°C to 150°C	(883) 1010, Con C, 10 cycles	100%	100%	
10	Electrical Test 25°C		100%	100%	
11	Constant acceleration	(883) 2001, 3000g, Y1	100%	100%	
12	Electrical Test 25°C		100%	100%	
13	PIND	(883) 2020, Con A	Optional	100%	
34	Electrical Test 25°C		100%	100%	
15	Isolation 100% @ 25°C	(MIL-STD 202) 301	100%	100%	
16	Electrical Test 25°C		100%	100%	
17	Electrical Test 125°C		Optional	100%	
18	Electrical Test -55°C		Optional	100%	
19	Switching time 100% @ 25°C		Optional	100%	
20	HTRB @ 125°C - 96 hrs	(883) 1015, con A	100%	100%	
21	Electrical Test 25°C		100%	100%	
22	Burn in @ 125°C	(883) 1015, con B	100% 160 hours	100% 160 hrs	
23	Electrical Test 25°C		100%	100%	
24	Burn in @ 125°C	(883) 1015, con B	N/A	100% 160 hrs	
25	Percentage defective allowable	Pre/post Burn-in electrical and delta at 25°C only	Max. 10%	Max. 2%	
26	Electrical Test 25°C	Group A - 9G1	100%	100%	
27	Electrical Test 125°C	Group A - SG2	100%	100%	
28	Electrical Test -55°C	Group A - 9G3	100%	100%	
29	Switching time 100% @ 25°C	Group A - 9G9	100%	100%	
30	Fine leak, Helium bomb, Leak detector	(883) 1014, Con A1	100%	100%	
31	Gross leak, Liquid bomb, -Bubble chamber	(883) 1014, Con C1	100%	100%	
32	Radiography	(883) 2012	Optional	100%	
33	External Visual	(883) 2009	100%	100%	



SCREENING IN ACCORDANCE WITH MIL-PRF 19500





The following screening flow includes the electrical tests between each screening step, the referenced test method from MIL-STD 750 and the sample basis for Class JANTX, JANTXV and JANS quality levels.

Operation	name of the same o	, MIL-PRF 19500	Class			
No.	Operation	MIL-PRF 19500	JANTX (L2)	JANTXV (L2)	JANS (L2S)	
1	Wire bond strength (ND)	(883) 2023	100%	100%	100%	
2.	Wire bond strength (D)	(750) 2037, Con D	4 devices	4 devices	8 devices	
8	Die Shear	(750) 2017	4 devices	4 devices	8 devices	
4	Internal Visual	(750) 2072	Optional	100%	100%	
5	Stabilization Bake		Optional	Optional	Optional	
	Electrical Test @ 25°C		100%	100%	100%	
7	Temp cycle (20 cycles @ -65°C to 150°C)	(750) 1051, Con F	100%	100%	100%	
	Electrical Test @ 25°C		100%	100%	100%	
	Constant acceleration	(750) 2006, 5000g, Y1	Optional	Optional	100%	
10	Electrical Test @ 25°C		100%	100%	100%	
11	P.I.N.D	(750) 2052, Con A	N/A	N/A	100%	
12	Electrical Test @ 25°C		N/A	N/A	100%	
13	Fine leak, Helium bomb, -Leak detector	(750) 1071 Con H1	Optional	Optional	Optional	
14	Gross leak, Liquid bomb, Bubble chamber	(750) 1071, Con C	Optional	Optional	Optional	
15	Serialisation of devices		N/A	N/A	100%	
16	Isolation 100% @ 25°C	(MIL-STD 202) 301	100%	100%	100%	
17	Electrical Test @ 25°C		100%	100%	100%	
18	Electrical Test @ 125°C		100%	100%	100%	
19	Electrical Test @ -55°C		100%	100%	100%	
20	Switching time @ 25°C		100%	100%	100%	
21	HTRB (125°C)	(750) 1039, Con A (80% VDS)	100% (48 hrs)	100% (48 hrs)	100% (48 hrs)	
22	Electrical Test @ 25°C		100% (24 hrs)	100% (24 hrs)	100% (16 hrs)	
23	Burn-In (125°C)	(750) 1039, Con B (80% VDS)	100% (160 hrs)	100% (160 hrs)	100% (240 hrs)	
24	Percentage defective allowable	Pre/post Burn-in electrical and delta at 25°C only	100% @ 10% PDA	100% @ 10% PDA	100% @ 5% PDA	
25	Electrical Test @ 25°C		100% (Group A, SG 2)	100% (Group A, SG 2)	100% (Group A, SG 2)	
26	Electrical Test @ 125°C		100% (Group A, SG 3)	100% (Group A, SG 3)	100% (Group A, SG 3)	
27	Electrical Test @ -55°C		100% (Group A, SG 3)	100% (Group A, SG 3)	100% (Group A, SG 3)	
28	Switching time @ 25°C		100% (Group A, SG4)	100% (Group A, SG4)	100% (Group A, SG4)	
29	Fine leak, Helium bomb, -Leak detector	(750) 1071 Con H1	100%	100%	100%	
30	Gross leak, Liquid bomb, Bubble chamber	(750) 1071, Con C	100%	100%	100%	
31	Radiography	(750) 2076	N/A	N/A	100%	
32	External Visual	(750) 2071	N/A	N/A	100%	



MIL-PRF 19500 TYPICAL QCI TESTING PROCESS FLOW

Group Sub		Parameters	Quantity (accept number)			
Group	Group	Parameters	TM	JANS	JANTX, JANTXV	
ľ	1	Visual and mechanical inspection	750-2071			
A (CI)	2	Static tests at +25°C	Datasheet	100%	100%	
A (CI)	3	Static tests at min and max. rated operating temp.	Datasheet	10076	100%	
	4	Dynamic test at +25°C	Datasheet			
		(JANS)		Large LOT (accept)	Small LOT (accept	
	- 1	Physical dimension	750-2066	22 (0)	8 (0)	
	2	Solderability	750-2026	15 leads (0)	6 leads (0)	
	7	Temperature cycling (100 cycles)	750-1051			
		Hermetic seal (fine and gross leak)	750-1071	22 (0)	6 (0)	
		Electrical measurements	GRP-A- SG2	22 (0)		
B (PI)	3	Decap internal visual	750-2075	6 (0)	6 (0)	
B (P1)		Bond strength	750-2037	22 wires (0) or 11 (0)	12 wires (0) or 6 (0)	
		SEM	750-2077	11 (0)	6 (0)	
		Die shear	750-2017	11 (0)	6 (0)	
	-	Intermittent operation life (2000 cycles)	750-1037			
	4	Electrical measurements	GRP-A- SG2	22 (0)	12 (0)	
		(JANTXV, JANTX)		Large LOT (accept)	Small LOT (accept	
T T	1	Solderability	750-2026	15 leads (0)	4 leads (0)	
		Temperature cycling (45 cycles incl. screening)	750-1051			
	2	Hermetic Seal (fine and gross leak)	750-1071	22 (0)	6 (0)	
	-	Electrical measurements	GRP-A-	22 (0)	0 (0)	
		Electrical measurements	SG2			
B (PI)		Steady state op. life (340 Hrs) or	750-1026			
		3 intermittent op. life (2000 cycles)	or 750-			
	3		1037	45 (0)	12 (0)	
		Electrical measurements	GRP-A- SG2			
	4	Decap internal visual	750-2075	1 (0)	1 (0)	



MIL-PRF 19500 TYPICAL QCI TESTING PROCESS FLOW

Group	Sub Group	Parameters	TM	Sample plan	Small LOT (accept)
	1	Physical dimensions (Not Req. JANS)	750-2066	15 (0)	6 (0)
		Thermal shock (25 cycles, con B)	750-1056		6 (0)
		Temperature cycling (45 cycles incl. screening)	750-1051		
	2	Terminal strength	750-2036	22 (0)	
	2	Hermetic seal (fine and gross leak)	750-1071	22 (0)	
		Electrical measurements	GRP-A- SG2		
C (PI)	3	Constant acceleration (5000g, Y1 only)	750-2006	22 (0)	6 (0)
		Electrical measurements	GRP-A- SG2		
	6	Steady state op. life (1000 Hrs) or intermittent op. life (6000 cycles)	750-1026 or 750- 1037	22 (0)	12 (0)
		Electrical measurements	GRP-A- SG2		
	7	Internal Gas Analysis - Moisture 10,000 ppmv limit	750-1018	3 (0)	3 (0)



MIL-PRF 38534 TYPICAL QCI TESTING PROCESS FLOW

Group	Sub Group	Parameters	Quantity (accept number)		
			TM	К	н
A (CI)	1	Static tests at +25°C	Datasheet	100%	100%
	2	Static tests at max. rated operating temp.	Datasheet	100%	100%
	3	Static tests at min. rated operating temp.	Datasheet	100%	100%
	9	Switching tests at +25°C	Datasheet	100%	100%
				-	
B (PI)	1	Physical dimension	883-2016	2 (0)	2 (0)
	4	Internal visual and mechanical	883-2014	1 (0)	1 (0)
	5	Bond strength: Ultrasonic (on hotplate)	883-2011	2 (0)	2 (0)
	6	Die shear strength	883-2019	2 (0)	2 (0)
	7	Solderability	883-2003	1 (0)	1 (0)
	8	Seal: a. Fine, b. Gross	883-1014	N/A	15 (0)
C (PI)	ĩ	External visual	883-2009	5 (0)	5 (0)
		Temperature Cycling	883-1010	5 (0)	5 (0)
		Constant acceleration	883-2001	X	5 (0)
		Seal (fine and gross)	883-1014	5 (0)	5 (0)
		PIND	883-2020	5 (0)	5 (0)
		Visual examination	883-1010	5 (0)	5 (0)
		End-point electrical	GRP-A	5 (0)	5 (0)
	2	Steady-state life test	883-1005	22 (0) or 5 (0)	22 (0) or 5 (0)
		End-point electrical	GRP-A	22 (0) or 5 (0)	22 (0) or 5 (0)
	3	Internal gas analysis	883-1018	3 (0) or 5 (1)	3 (0) or 5 (1)
		Moisture 10,000 ppmv limit			
D (PI)	1	Thermal shock	883-1011	5 (0)	5 (0)
		Stabilization bake	883-1011	5 (0)	5 (0)
		Lead integrity	883-2004	1 (0)	1 (0)
		Seal: a. Fine, b. Gross	883-1014	5 (0)	5 (0)



Summary of key differences between MIL-PRF 19500 and MIL-PRF 38534 for space level testing:

	MIL-PRF 19500 - JANS	MIL-PRF 38534 – Class K		
No. of Operation	31	33		
(Screening) Steps	.	33		
Optional				
Hermeticity	Occurs post P.I.N.D	Occurs post Internal Visual		
Testing				
Temp cycle – No.	20	10		
of Temp Cycles				
Acceleration -	5000g	3000g		
Amount of g force		5555		
HTRB – No. of	48	96		
hours	45	55		
Burn-in – No. of	240 hrs in one successive burn-in	320 hrs (2 \times 160 hrs with interim electrical)		
hours	240 ms m one successive built m			
PDA post burn-in	rn-in 5% after 240 hrs burn-in 2% after second 160 hrs burn			



DISCLAIMER

The information provided on the datasheet is for preliminary and general information only. We do not warrant that the information contained on the datasheet is suitable for your intended use, nor do we accept responsibility for loss suffered as a result of reliance by you upon the accuracy or currency of information contained on the datasheet. In particular, you should not make any investment or commercial decision on the basis of the information contained on the datasheet. You should obtain independent professional advice and make your own further enquiries before making any investment or commercial decision or taking any further action in any way related to the information contained on the datasheet.

We are not aware of any inaccuracy in the information contained on the datasheet. However, we do not warrant the accuracy, adequacy or completeness of such information.

We reserve the right to remove or alter any of the information contained on the datasheet at any time. However, we do not guarantee the currency of the information contained on the datasheet, nor do we undertake to keep the datasheet updated.

ISOCOM Limited
2 Fern Court
Bracken Hill Business Park
Peterlee
County Durham
SR8 2RR
United Kingdom

W – www.isocom.uk.com E – sales@isocom.uk.com T - +44 (0) 191 416 6546









ISOCOM Limited is AS9100 certified for the design and manufacture of electronic and optoelectronic components.